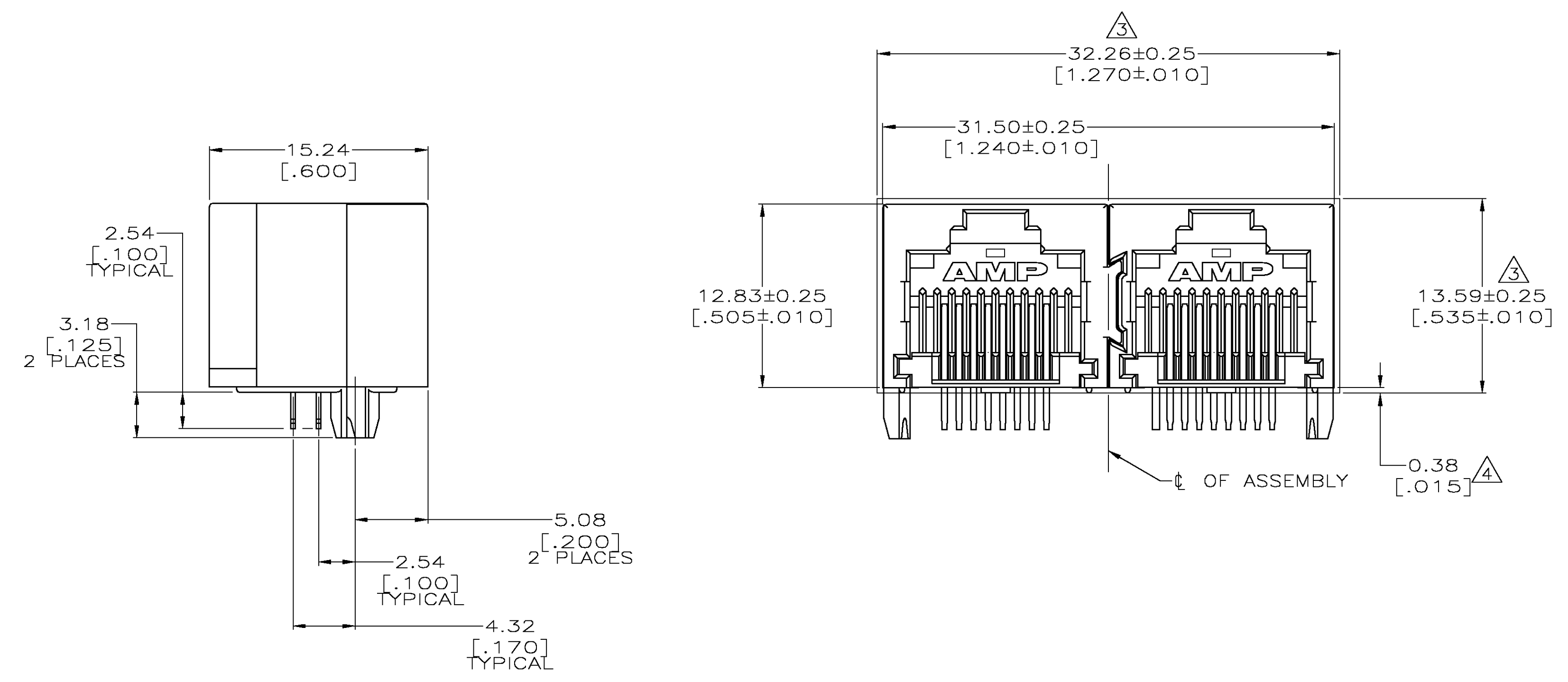
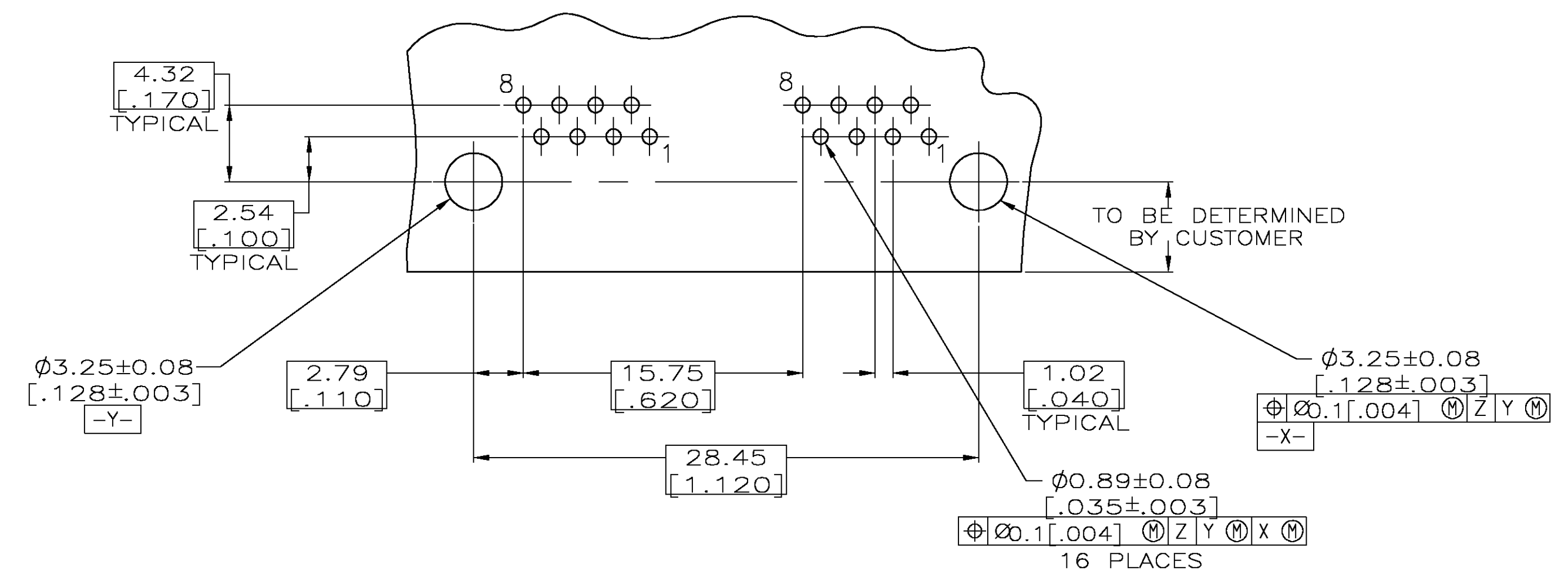
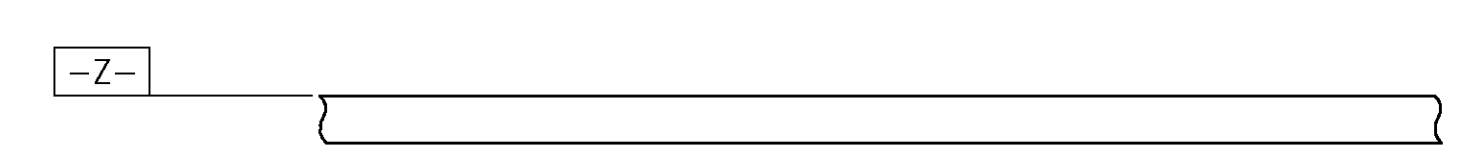


LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	BY	APP'D
AA	22	A	ECOS11-0201-04	08JUNE2005	LAM SF



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 µm [.000050] MINIMUM THICK NICKEL.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
 ▲ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

5406526-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN T. WOOTEN / 08JUNE2005	Tyco Electronics Corporation	
DIMENSIONS: mm		CHK J. WESTMAN / 08JUNE2005	Harrisburg, Pa 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APP'D S. FLICKINGER / 08JUNE2005	NAME INVERTED MOD JACK ASSEMBLY, 1x2	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC 108-1163-4	SIZE -	
2 PLC ± -	3 PLC ± -	APPLICATION SPEC 114-2154	CAGE CODE -	DRAWING NO -
4 PLC ± -	ANGLES ± -	FINISH -	RESTRICTED TO -	SCALE 4:1
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT -	A1 00779 ©=5406526	SHEET 1 OF 1
CUSTOMER DRAWING		REV A		

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